
PXI-6541

Specifications

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PXI-6541 Specifications

These specifications apply to the PXI-6541 with 1 MBit, 8 MBit, and 64 MBit of memory per channel.



Note All values were obtained using a 1 m cable (SHC68-C68-D4 recommended). Performance specifications are not guaranteed when using longer cables.

Definitions

Warranted specifications describe the performance of a model under stated operating conditions and are covered by the model warranty.

Characteristics describe values that are relevant to the use of the model under stated operating conditions but are not covered by the model warranty.

- **Typical** specifications describe the performance met by a majority of models.
- **Nominal** specifications describe an attribute that is based on design, conformance testing, or supplemental testing.

Specifications are **Typical** unless otherwise noted.

Conditions

Typical values are representative of an average unit operating at room temperature.

Channels

Data	
Number of channels	32

Direction control	Per channel
Programmable Function Interface (PFI)	
Number of channels	4
Direction control	Per channel
Clock terminals	
Input	3
Output	2

Generation Channels

Channels	Data DDC CLK OUT PFI <0..3>
Signal type	Single-ended

Table 1. Voltage Levels, I = 100 μ A

Logic family, into 1 M Ω	Low		High	
	Typical	Maximum	Minimum	Typical
1.8 V	0 V	0.1 V	1.7 V	1.8 V
2.5 V			2.4 V	2.5 V

Logic family, into 1 M Ω	Low		High	
	Typical	Maximum	Minimum	Typical
3.3 V TTL (5 V TTL compatible)			3.2 V	3.3 V

Output impedance	50 Ω , nominal
Maximum DC drive strength, by logic family	
1.8 V	± 8 mA
2.5 V	± 16 mA
3.3 V	± 32 mA
Data channel driver enable/disable control	Software-selectable: per channel
Channel power-on state ^[1]	Drivers disabled, 50 k Ω input impedance
Output protection	
Range	0 V to 5 V
Duration	Indefinite

Acquisition Channels

Channels	Data
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	STROBE PFI <0..3>
Signal type	Single-ended

Table 2. Voltage Levels

Logic family	Maximum Low Threshold	Minimum High Threshold
1.8 V	0.45 V	1.35 V
2.5 V	0.75 V	1.75 V
3.3 V TTL (5 V TTL compatible)	1.00 V	2.30 V

Input impedance ^[2]	50 k Ω
Input protection range ^[3]	-1 V to 6 V

Timing

Sample Clock

Sources	<ol style="list-style-type: none"> 1. On Board clock (internal voltage-controlled crystal oscillator [VCXO] with divider) 2. CLK IN (SMB connector) 3. PXI_STAR (PXI backplane) 4. STROBE (Digital Data & Control [DDC] connector; acquisition only)
Frequency range	

On Board clock	48 Hz to 50 MHz, Configurable to 200 MHz/ N ; $4 \leq N \leq 4,194,304$
CLK IN	20 kHz to 50 MHz
PXI_STAR	48 Hz to 50 MHz
STROBE	48 Hz to 50 MHz
Relative delay adjustment	
Range	0.0 to 1.0 Sample clock periods
Resolution	10 ps
Exported Sample Clock	
Destinations ^[5]	<ol style="list-style-type: none"> 1. DDC CLK OUT (DDC connector) 2. CLK OUT (SMB jack connector)
Delay (δ_C), for clock frequencies ≥ 25 MHz	
Range	0.0 to 1.0 Sample clock periods
Resolution	1/256 of Sample clock period
Jitter, using On Board clock	

Period	20 ps _{rms} , typical
Cycle-to-cycle	35 ps _{rms} , typical

Generation Timing

Channels	Data DDC CLK OUT PFI <0..3>
Data channel-to-channel skew	±600 ps, typical
Maximum data channel toggle rate	25 MHz
Data position modes	Sample clock rising edge Sample clock falling edge Delay from Sample clock rising edge
Generation data delay (δ_G), for clock frequencies ≥ 25 MHz	
Range	0.0 to 1.0 Sample clock periods
Resolution	1/256 of Sample clock period
Exported Sample clock offset (t_{CO})	Software-selectable: 0.0 ns or 2.5 ns (default)

Time delay from Sample clock (internal) to DDC connector (t _{SCDDC})	15 ns, typical
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Table 3. Generation Provided Setup and Hold Times

Exported Sample Clock Mode and Offset	Voltage Family	Time from Rising Clock Edge to Data Transition (t _{PCO})	Minimum Provided Setup Time (t _{PSU})	Minimum Provided Hold Time (t _{PH})
Noninverted, 2.5 ns	1.8 V	2.5 ns, typical	t _p - 5.5 ns	0.5 ns
	2.5 V		t _p - 4.5 ns	0.9 ns
	3.3 V/5.0 V		t _p - 4.5 ns	1 ns
Inverted, 0 ns	1.8 V	t _p /2	t _p /2 - 3.5 ns	(t _p /2) - 1.5 ns
	2.5 V		t _p /2 - 2.5 ns	
	3.3 V/5.0 V		t _p /2 - 2 ns	



Note Provided setup and hold times account for maximum channel-to-channel skew and jitter.

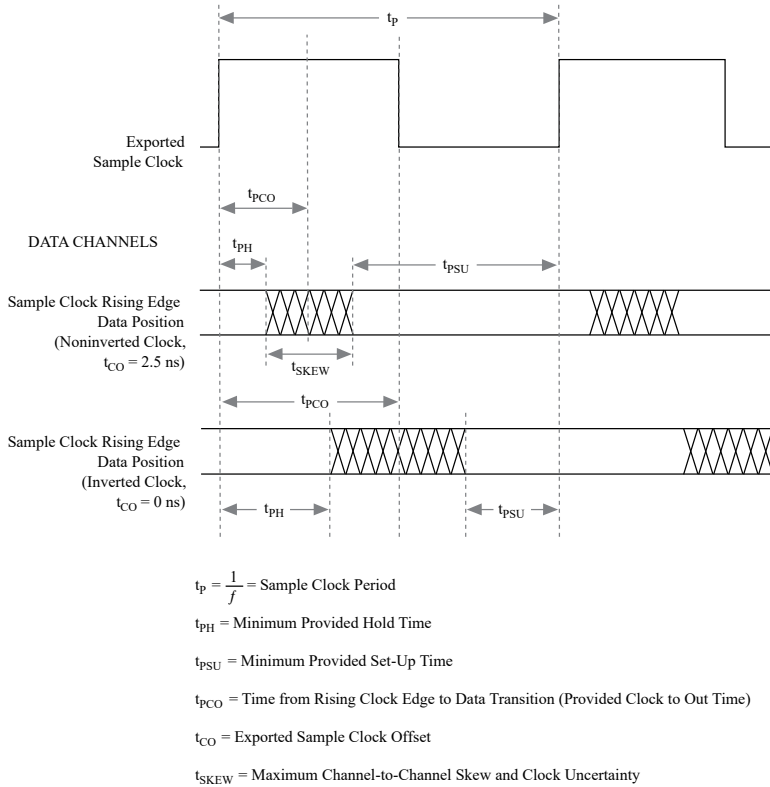
The table values provided assume the following data position is set to Sample clock rising edge and the Sample clock is exported to the DDC connector and includes worst-case effects of channel-to-channel skew, inter-symbol interference, and jitter. Other combinations of exported Sample clock mode and offset are also allowed. The values presented are from the default case (noninverted clock with 2.5 ns offset) and for providing balanced setup and hold times (inverted clock with 0 ns offset).

To determine the appropriate exported Sample clock mode and offset for your PXI-6541 generation session, compare the setup and hold times from the datasheet of your device under test (DUT) to the values in this table. Select the exported Sample clock mode and offset such that the PXI-6541 provided setup and hold times are greater than the setup and hold times required for the DUT.

Specified timing relationships apply at the DDC connector and at high-speed DIO

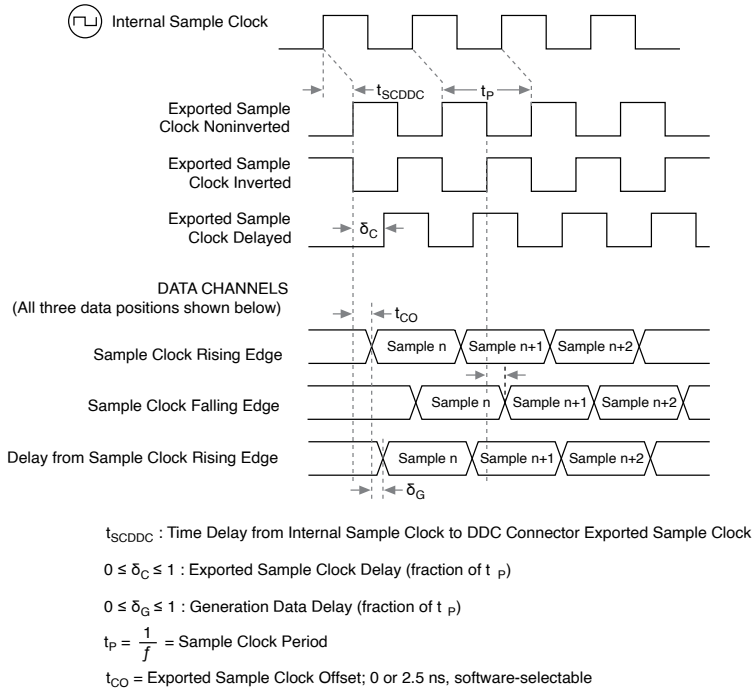
accessory terminals. Any signal routing, clock splitting, buffers, or translation logic can impact this relationship. If multiple copies of DDC_CLK_OUT are necessary, use a zero buffer to preserve this relationship.

Figure 1. Generation Provided Setup and Hold Times Timing Diagram



Note Provided setup and hold times account for maximum channel-to-channel skew and jitter.

Figure 2. Generation Timing Diagram



Acquisition Timing

Channels	Data STROBE PFI <0..3>
Channel-to-channel skew	±600 ps, typical
Data position modes	Sample clock rising edge Sample clock falling edge Delay from Sample clock rising edge
Setup and hold times	
To STROBE ^[6]	

Setup time (t_{SUS})	3.1 ns, maximum
Hold time (t_{HS})	2.7 ns, maximum
To Sample clock^[7]	
Setup time (t_{SUSC})	0.4 ns
Hold time (t_{HSC})	0 ns
Time delay from DDC connector data to internal Sample clock (t_{DDCSC})	10 ns, typical
Acquisition data delay (δ_A), for clock frequencies ≥ 25 MHz	
Range	0.0 to 1.0 Sample clock periods
Resolution	1/256 of Sample clock period

Figure 3. Acquisition Timing Diagram Using STROBE as the Sample Clock

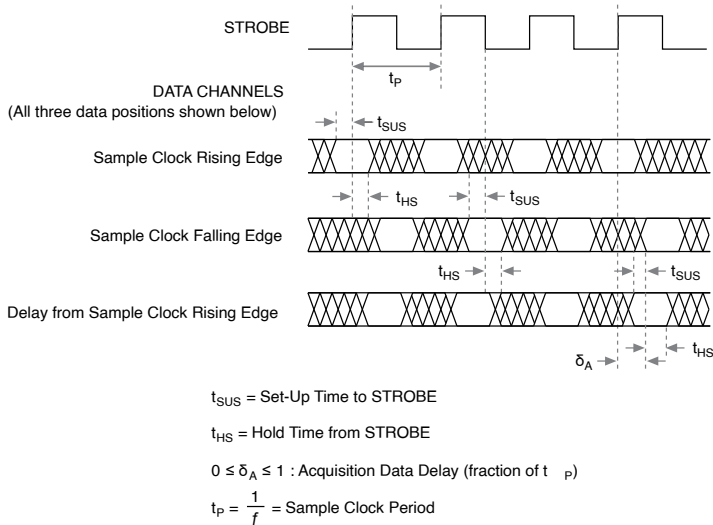
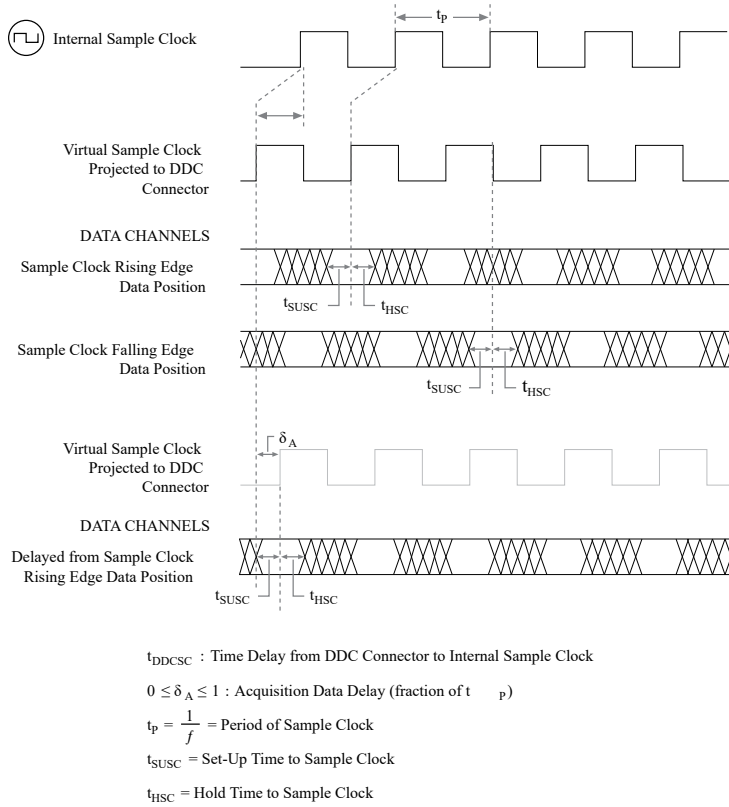


Figure 4. Acquisition Timing Diagram with Sample Clock Sources Other than STROBE



CLK IN

Connector	SMB jack
Direction	Input
Signal type	Single-ended
Destinations	<ol style="list-style-type: none"> Reference clock for the phase-locked loop (PLL) Sample clock
Input coupling	AC

Input protection	± 10 VDC
Input impedance	Software-selectable: 50 Ω (default) or 1 k Ω
Minimum detectable pulse width	4 ns
Clock requirements	Free-running (continuous) clock

As Sample Clock

Table 4. External Sample Clock Range

Voltage Range (V_{pk-pk})	Sine Wave	Square Wave	
	Frequency Range	Frequency Range	Duty Cycle
0.65 to 5.0	5.5 MHz to 50 MHz	20 kHz to 50 MHz	• 25% to 75%
1.0 to 5.0	3.5 MHz to 50 MHz	—	—
2.0 to 5.0	1.8 MHz to 50 MHz	—	—

As Reference Clock

Frequency range	10 MHz \pm 50 ppm
Voltage range	0.65 V_{pk-pk} to 5.0 V_{pk-pk}
Duty cycle	25% to 75%

STROBE

Connector	DDC
Direction	Input
Destination	Sample clock (acquisition only)
Frequency range	48 Hz to 50 MHz
Duty cycle range ^[8]	25% to 75%
Minimum detectable pulse width ^[9]	4 ns
Voltage thresholds	Refer to Acquisition Timing in the Timing section.
Clock requirements	Free-running (continuous) clock
Input impedance ^[10]	Software-selectable: 50 k Ω

PXI_STAR

Connector	PXI backplane
Direction	Input

Signal type	Single-ended
Destinations	<ol style="list-style-type: none"> 1. Sample clock 2. Start trigger 3. Reference trigger (acquisition sessions only) 4. Advance trigger (acquisition sessions only) 5. Pause trigger (generation sessions only) 6. Script trigger <0..3> (generation sessions only)
Frequency range	48 Hz to 50 MHz
Clock requirements	Free-running (continuous) clock

CLK OUT

Connector	SMB jack
Direction	Output
Sources	<ol style="list-style-type: none"> 1. Sample clock (excluding STROBE) 2. Reference clock (PLL)
Output impedance	50 Ω , nominal

Electrical characteristics	Refer to Generation Timing in the Timing section.	
Maximum drive current		
At 1.8 V		8 mA
At 2.5 V		16 mA
At 3.3 V		32 mA
Logic type	Generation logic family setting: 1.8 V, 2.5 V, 3.3 V	

DDC CLK OUT

Connector	DDC
Direction	Output
Source ^[11]	Sample clock
Electrical characteristics	Refer to Generation Timing in the Timing section.

Reference Clock (PLL)

Sources ^[12]	1. PXI_CLK10, (PXI backplane)
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	2. CLK IN (SMB jack connector) 3. None (On Board clock not locked to a reference)
Destination	CLK OUT (SMB jack connector)
Lock time	400 ms, typical
Frequencies	10 MHz \pm 50 ppm
Duty cycle range	25% to 75%

Waveform

Memory and Scripting

Memory architecture	The PXI-6541 uses Synchronization and Memory Core (SMC) technology in which waveforms and instructions share onboard memory. Parameters such as number of script instructions, maximum number of script instructions, maximum number of waveforms in memory, and number of samples (S) available for waveform storage are flexible and user defined.	
Onboard memory size ^[13]		
1 Mbit/channel		
Acquisition	1 Mbit/channel (4 MBytes total)	
Generation	1 Mbit/channel (4 MBytes total)	
8 Mbit/channel		

Acquisition	8 Mbit/channel (32 MBytes total)
Generation	8 Mbit/channel (32 MBytes total)
64 Mbit/channel	
Acquisition	64 Mbit/channel (256 MBytes total)
Generation	64 Mbit/channel (256 MBytes total)
Generation	
Single waveform mode	Generates a single waveform once, <i>n</i> times, or continuously.
Scripted mode ^[14]	Generates a simple or complex sequences of waveforms.
Finite repeat count	1 to 16,777,216
Waveform quantum ^[15]	Waveform must be an integer multiple of 2 S (samples).

Table 5. Generation Minimum Waveform Size, Samples (S)^[16]

Configuration	Sample Rate
	50 MHz
Single waveform	2 S
Continuous waveform	16 S
Stepped sequence	64 S
Burst sequence	256 S

Acquisition	
Minimum record size ^[17]	1 S
Record quantum	1 S
Total records	2,147,483,647, maximum
Total pre-Reference trigger samples	0 up to full record
Total post-Reference trigger samples	0 up to full record

Triggers

Trigger Types	Sessions	Edge Detection	Level Detection
1. Start	Acquisition and generation	Rising or falling	—
2. Pause	Acquisition and generation	—	High or low
3. Script <0..3>	Generation	Rising or falling	High or low
4. Reference	Acquisition	Rising or falling	—
5. Advance	Acquisition	Rising or falling	—

Sources	<ol style="list-style-type: none"> 1. PFI 0 (SMB jack connector) 2. PFI <1..3> (DDC connector) 3. PXI_TRIG <0..7> (PXI backplane) 4. PXI_STAR (PXI backplane)
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	<p>5. Pattern match (acquisition sessions only)</p> <p>6. Software (user function call)</p> <p>7. Disabled (do not wait for a trigger)</p>
Destinations ^[18]	<p>PFI 0 (SMB jack connector)</p> <p>PFI <1..3> (DDC connector)</p> <p>PXI_TRIG <0..6> (PXI backplane)</p>
Minimum required trigger pulse width	
Generation	30 ns
Acquisition	Acquisition triggers must meet setup and hold time requirements.

Table 6. Trigger Rearm Time

Type	Typical	Maximum
Start to Reference	57 S	64 S
Start to Advance	138 S	143 S
Reference to Reference	132 S	153 S

Delay from Pause trigger to Pause state^[19]	
Generation sessions	32 Sample clock periods + 150 ns
Acquisition sessions	Data synchronous

Delay from trigger to digital data output	32 Sample clock periods + 160 ns
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Events

Event Types	Sessions
1. Marker <0..3>	Generation
2. Data Active	Generation
3. Ready for Start	Acquisition and generation
4. Ready for Advance	Acquisition
5. End of Record	Acquisition

Destinations ^[20]	<ol style="list-style-type: none"> 1. PFI 0 (SMB jack connector) 2. PFI <1..3> (DDC connector) 3. PXI_TRIG <0..6> (PXI backplane)
Marker time resolution (placement)	Markers must be placed at an integer multiple of 2 S (samples).

Miscellaneous

Warm-up time	15 minutes
On Board clock characteristics (valid only when PLL reference source is set to None)	
Frequency accuracy	±100 ppm

Temperature stability	±30 ppm
Aging	±5 ppm first year

Software

Driver Software

Driver support for this device was first available in NI-HSDIO 1.2.

NI-HSDIO is an IVI-compliant driver that allows you to configure, control, and calibrate the PXI-6541. NI-HSDIO provides application programming interfaces for many development environments.

Application Software

NI-HSDIO provides programming interfaces, documentation, and examples for the following application development environments:

- LabVIEW
- LabWindows™/CVI™
- Measurement Studio
- Microsoft Visual C/C++
- .NET (C# and VB.NET)

NI Measurement Automation Explorer

NI Measurement Automation Explorer (MAX) provides interactive configuration and test tools for the PXI-6541. MAX is included on the NI-HSDIO media.

Power

VDC	Current Draw, Typical	Current Draw, Maximum
+3.3 V	1.6 A	1.8 A

VDC	Current Draw, Typical	Current Draw, Maximum
+5 V	1.2 A	1.7 A
+12 V	0.25 A	0.4 A
-12 V	0.06 A	0.10 A

Total power	15 W, typical 20.5 W, maximum
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Physical Specifications

Dimensions	Single 3U, CompactPCI slot, PXI compatible, 21.6 cm × 2.0 cm × 13.1 cm (8.5 in × 0.8 in × 5.16 in)
Weight	343 g (12.1 oz)

I/O Connectors

Label	Connector Type	Description
CLK IN	SMB jack	External Sample clock, external PLL reference input
PFI 0		Events, triggers
CLK OUT		Exported Sample clock, exported Reference clock
DIGITAL DATA & CONTROL	68-pin VHDCI connector	Digital data channels, exported Sample clock, STROBE, events, triggers

Environment



Note To ensure that the PXI-6541 cools effectively, follow the guidelines in the ***Maintain Forced Air Cooling Note to Users*** included with the PXI-6541 or available at ni.com/manuals. The PXI-6541 is intended for indoor use only.

Operating temperature	0 °C to 55 °C in all NI PXI chassis except the following: 0 °C to 45 °C when installed in an NI PXI-1000B or NI PXI-101x chassis
Operating relative humidity	10 to 90% relative humidity, noncondensing (meets IEC 60068-2-56)
Storage temperature	-20 °C to 70 °C
Storage relative humidity	5 to 95% relative humidity, noncondensing (meets IEC 60068-2-56)
Operating shock	30 g, half-sine, 11 ms pulse (meets IEC 60068-2-27; test profile developed in accordance with MIL-PRF-28800F)
Operating vibration	5 Hz to 500 Hz, 0.31 g _{rms} (meets IEC 60068-2-64)
Storage shock	50 g, half-sine, 11 ms pulse (meets IEC 60068-2-27; test profile developed in accordance with MIL-PRF-28800F)
Storage vibration	5 Hz to 500 Hz, 2.46 g _{rms} (meets IEC 60068-2-64; test profile exceeds requirements of MIL-PRF-28800F, Class B)

Altitude	0 to 2,000 m above sea level (at 25 °C ambient temperature)
Pollution degree	2

Compliance and Certifications

Safety Compliance Standards

This product is designed to meet the requirements of the following electrical equipment safety standards for measurement, control, and laboratory use:

- IEC 61010-1, EN 61010-1
- UL 61010-1, CSA C22.2 No. 61010-1



Note For safety certifications, refer to the product label or the [Product Certifications and Declarations](#) section.

Electromagnetic Compatibility

This product meets the requirements of the following EMC standards for electrical equipment for measurement, control, and laboratory use:

- EN 61326-1 (IEC 61326-1): Class A emissions; Basic immunity
- EN 55011 (CISPR 11): Group 1, Class A emissions
- AS/NZS CISPR 11: Group 1, Class A emissions
- FCC 47 CFR Part 15B: Class A emissions
- ICES-001: Class A emissions



Note For EMC declarations, certifications, and additional information, refer to the [Online Product Certification](#) section.

To meet EMC compliance, the following cautions apply:



Caution The SHC68-C68-D4 shielded cables must be used when operating the PXI-6541.



Caution EMC filler panels must be installed in all empty chassis slots.

CE Compliance

This product meets the essential requirements of applicable European Directives, as follows:

- 2014/35/EU; Low-Voltage Directive (safety)
- 2014/30/EU; Electromagnetic Compatibility Directive (EMC)
- 2011/65/EU; Restriction of Hazardous Substances (RoHS)
- 2014/53/EU; Radio Equipment Directive (RED)
- 2014/34/EU; Potentially Explosive Atmospheres (ATEX)

Product Certifications and Declarations


Refer to the product Declaration of Conformity (DoC) for additional regulatory compliance information. To obtain product certifications and the DoC for NI products, visit ni.com/product-certifications, search by model number, and click the appropriate link.

Environmental Management


NI is committed to designing and manufacturing products in an environmentally responsible manner. NI recognizes that eliminating certain hazardous substances from our products is beneficial to the environment and to NI customers.

For additional environmental information, refer to the ***Engineering a Healthy Planet*** web page at ni.com/environment. This page contains the environmental regulations and directives with which NI complies, as well as other environmental information not included in this document.

EU and UK Customers

-  **Waste Electrical and Electronic Equipment (WEEE)**—At the end of the product life cycle, all NI products must be disposed of according to local laws and regulations. For more information about how to recycle NI products in your region, visit ni.com/environment/weee.

电子信息产品污染控制管理办法（中国RoHS）

-  **中国RoHS**—NI符合中国电子信息产品中限制使用某些有害物质指令 (RoHS)。关于NI中国RoHS合规性信息，请登录 ni.com/environment/rohs_china。(For information about China RoHS compliance, go to ni.com/environment/rohs_china.)